

1 Customer drawings

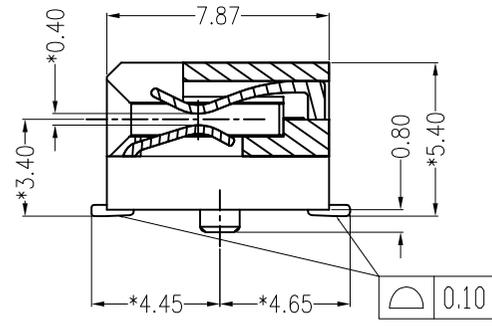
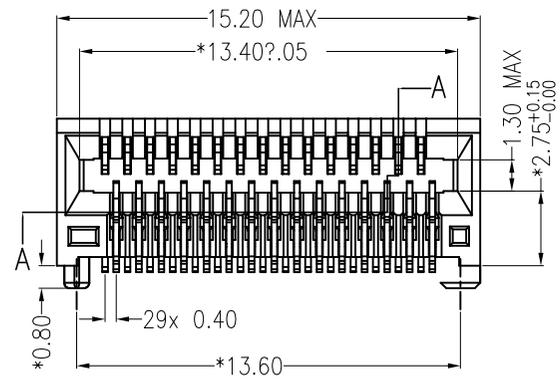
NOTE:
 MATERIAL:
 1. TERMINAL: COPPER ALLOY
 2. HOUSING: HIGH TEMPERATURE THERMOPLASTIC
 GLASS FILLED UL 94V-0. COLOR: BLACK

PLATED:
 OPTION1:
 1.1. CONTACT AREA : PLATING GOLD 0.38 MICROMETERS MINIMUM
 OVER 1.25~2.54 MICROMETERS NICKEL.
 1.2. SURFACE MOUNT CONTACT: 1.25~2.54 MICROMETERS MATTE TIN
 OVER 1.25~2.54 MICROMETERS NICKEL.

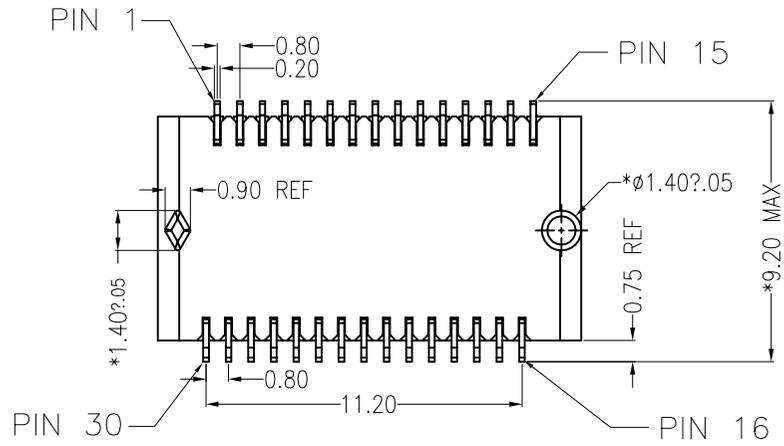
OPTION2:
 2.1. CONTACT AREA : PLATING GOLD 0.76 MICROMETERS MINIMUM
 OVER 1.25~2.54 MICROMETERS NICKEL.
 2.2. SURFACE MOUNT CONTACT: 1.25~2.54 MICROMETERS MATTE TIN
 OVER 1.25~2.54 MICROMETERS NICKEL.

ELECTRICAL:
 1. CONTACT CURRENT RATING:0.5 Amps MAX.
 2. VOLTAGE RATING:30 Volts AC (RMS)/DC MAX.
 3. CONTACT RESISTANCE: ΔR 10 MILLIOHMS MAXIMUM FOR SIGNAL CONTACTS.
 4. DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN.

ENVIRONMENT:
 1. OPERATION: -40°C~+85°C.
 2. STORAGE: -55°C~+105°C.
 3. REFLOW SOLDERING TEMPERATURE:260° MAXIMUM FOR 30 SECONDS.
 4. ROHS COMPLIANT



SECTION A-A



ROHS PART NUMBER	DESCRIPTION	CONTACT PLATING GOLD
81-141-40001-1	CONNECTOR, XFP 1*1 SMT Type	0.38 MICROMETERS
81-141-50001-1	CONNECTOR, XFP 1*1 SMT Type	0.76 MICROMETERS

自由公差			
长度尺寸	角度尺寸		
X. ±0.35	X° ±0.5°		
.XX ±0.35	.X° ±0.5°		
.XX ±0.25	.XX° ±0.5°		
.XXX ±0.15			
单位 mm	比例 1:1		
A4	页次 1 of 2		

版次	修改说明	ECN 编号	核准

设计

审核

核准

ETLINK 深圳市益晟康科技有限公司
ETLINK SHENZHEN ETLINK TECHNOLOGY CO.,LTD

品名: XFP 1x1 CONNECTOR

料号: SEE TABLE

图号: ESFP15032704-C 版本: A

